

### **REMARKS**

Claims 1, 2 and 4-20 are pending in the present application. Claims 15-20 are withdrawn. Claim 1 is herein amended. Support for the amendment is set forth below. Applicants' undersigned representative thanks Examiners Owens and Gebremariam for the courtesies extended during the telephone interview of August 29, 2006. Applicants' separate record of the substance of the interview is set forth below.

### **Applicants' Response to Claim Rejections under 35 U.S.C. §103(a)**

Claims 1-2, 4-6, 8-10 and 13-14 stand rejected under 35 U.S.C. 103(a) as being unpatentable over **Chakravorty**, US patent No. 6,611,419 in view of **Gnadinger**, US patent No. 5,229,647. In response thereto applicants have amended the claims to more specifically state the subject matter regarded as the invention. Specifically, applicants have clarified that the through holes of the current invention are only straight.

As discussed in the course of the interview, Figs. 1A to 1F of the current application illustrate that a support substrate 11 of a semiconductor material 11 is formed with through holes 14 by etching through the semiconductor material. The through holes are then filled with conductive material. Hence, there are no bends formed in the through holes as they extend through the support substrate.

Contrary, as discussed in the course of the interview, **Chakravorty** teaches that bends 322, 324 occur within the support substrate 310. Hence, **Chakravorty** does not disclose only straight through holes through the support substrate as required by claim 1.

Further, as also briefly discussed in the course of the interview, Applicants respectfully submit that one of skill in the art is not motivated to combine that multilayer ceramic substrate of **Chakravorty** with a stacked semiconductor memory as taught by **Gnadinger**. **Chakravorty** is directed to ceramic substrate technology. See Column 4, lines 52-53. **Chakravorty's** taught embodiments are directed to ceramic and PCB substrates. See column 5, lines 37-40. Although **Chakravorty** states that the substrates may be of any type, manufacturing processes of the ceramic substrate and the semiconductor substrate are completely different and neither reference provides sufficient teaching to utilize the others' material. Wherefore, there is insufficient teaching in the combination of the references to lead the skilled artisan to make the current invention.

In view of the aforementioned amendments and accompanying remarks, Applicants submit that the claims, as herein amended, are in condition for allowance. Applicants request such action at an early date.

If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney to arrange for an interview to expedite the disposition of this case.

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Amendment under 37 C.F.R. §1.111  
Amendment Filed: September 1, 2006

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

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